

In the Claims

There are no claim amendments.

CLAIMS

Claims 1-3 (Cancelled).

Claims 4 and 5 (Withdrawn).

6. (Previously Amended) The method of bonding solder balls of claim 12, wherein said exposing comprises laser bonding the balls with their associated bond pads.

Claim 7 (Withdrawn).

8. (Previously Amended) The method of bonding solder balls of claim 12, wherein said exposing comprises laser bonding the balls with their associated bond pads by fixing the position of a laser beam and moving the frame relative to the laser beam from ball-to-ball.

Claims 9-11 (Withdrawn).

12. (Previously Amend d) A method of bonding solder balls to bond pads on a substrate comprising:

placing at least portions of a plurality of solder balls within a frame and in registered alignment with individual bond pads over a substrate by dipping the substrate into a volume of balls; and

while the ball portions are within the frame, exposing the balls to bonding conditions effective to bond the balls with their associated bond pads, wherein said placing comprises placing said ball portions on fluxless bond pad surfaces.

Claim 13 (Cancelled).

14. (Previously Amended) The method of claim 18, wherein the holes are sized to receive a majority portion of an associated solder ball.

15. (Previously Amended) The method of claim 18, wherein the holes are sized to receive a majority portion of only one associated solder ball.

Claims 16 and 17 (Withdrawn).

18. (Previously Amended) A method of bonding solder balls to bond pads on a substrate comprising:

providing a frame having a plurality of holes sized to receive individual solder balls;

delivering individual balls into the holes from over the frame by dipping the frame into a volume of balls;

c1 placing the balls into registered alignment, while the balls are in the holes, with a plurality of individual bond pads over a substrate; and

bonding the balls in the absence of flux with their individual associated bond pads, wherein said placing of the balls into registered alignment comprises moving the frame to proximate the substrate before any of the balls are delivered into the holes.

Claim 19 (Cancelled).

20. (Previously Amended) The method of claim 18, wherein the bonding of the balls comprises laser bonding the balls with their individual associated bond pads.

Claim 21 (Withdrawn).

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22. (Previously Amended) The method of claim 18, wherein the bonding of the balls comprises laser bonding the balls with their individual associated bond pads by fixing the position of a laser beam and moving the frame relative to the laser beam from ball-to-ball to effectuate the bonding.

Claims 23-44 (Cancelled).

Claims 45 and 46 (Withdrawn).